



5310

Manual Gold Ballbonder

The Gold-Ball-Bonder 5310 can process gold wires from 17,5 to 50 μm , using the bumping mode as well as the stitchbond mode .

Due to the motor driven Z-axis you work always with repeatable results. Additionally every parameter can be saved to the internal harddisk.

You always work with repeatable results – also after a lot of years. The handling, supported by a colour display and the input with an shuttle-wheel make the programming of the machine very easy. The operator can create different kinds of loops with the manipulator system. Operators require only a minimum of training, making the 5310 manual ball bonder the ideal choice for prototype, rework and small-scale production.

The 5310 is perfect suited for complex bond- tasks, optimal quality and the most favourable price. This machine is the right choice for such applications.

Specifications

Concept	DC-motor driven Z-linear-axis, Single-board-PC, menu-controlled Teach-In, Operating and menu access via shuttle-wheel with push-button
<i>Wire-types</i>	Au-wire: 17,5...50 μm on 2" spool Optional on 1/2" spool
<i>Bondhead</i>	Contactless electronic Touchdown-Sensor US-Generator 0...5 W programmable, 60 kHz standard, other frequencies optional Negative Flame-Off Bondforce 15 until 150 cN electrically adjustable Capillaries: 9 – 16mm length Step precision : 1 μm
Display	6,5" TFT Color-Display, 640x480 Pixel (VGA)
<i>Working area</i>	Bondhead linear Z travel: 60 mm; Standard workheight: 55mm Manipulator in X and Y: 18 x 18 mm Respond reduction: 1:7
Substrate-holder	Digitally controlled heated stage, up to 360°C Standard \varnothing 60 mm for tools up to 2" x 2", mechanical clamping 4" x 4", 80 mm and 95 mm \varnothing optional, also with vacuum (Attention: 4x4" up to 200°C)
Control-modes:	Manual, semi-automatic Programmeline-Step for testing via Shuttle-wheel
<i>Loop-types:</i>	Ball-Wedge, Bumping, Reverse, Stitch programmable
<i>Dimensions</i>	Height: 400mm, width: 630mm, depth: 580mm, weight approx. 30kg
<i>Programme Memory</i>	internal hard disk

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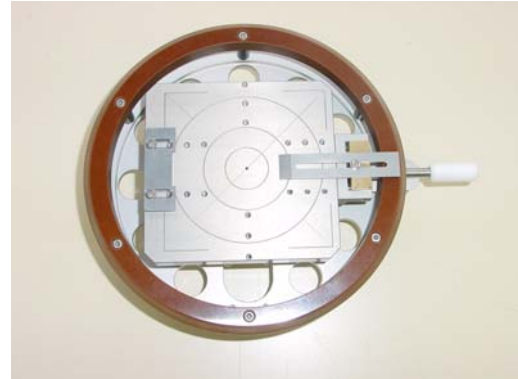
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Connections: 100...230 VAC, single-phase; pot. Air-pressure
/ vacuum Ø 6 mm

Substrathalter

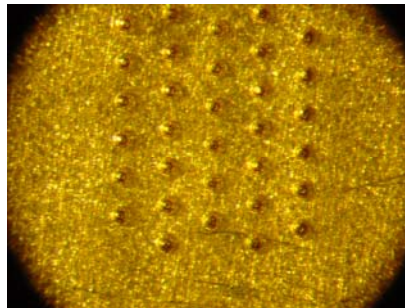
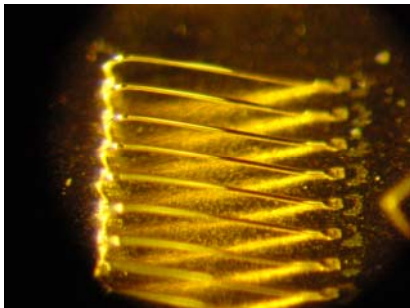


Part No.: 5-0427-150-0
Workholder d=80mm
heated with vacuum
+Adapter



Option
4-0402-210-0
heated
4x4", mechanical clamping and vacuum

Rev_04
06_2010



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